



100% Material Declaration Data Sheet FGG320

PK106 (v1.2) September 27, 2006

Material Declaration Data Sheet

Average Weight: 1.2528 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0535	4.27%
	Silicon	7440-21-3	100.00		0.0535	
Die Attach Material					0.0057	0.45%
	Silver	7440-22-4	78.00		0.0044	
	Resin	Trade Secret	22.00		0.0013	
Mold Compound					0.5858	46.76%
	Epoxy Resins	Trade Secret	12.00		0.0703	
	SiO2	60676-86-0	88.00	Filler	0.5155	
Laminate					0.2588	20.66%
	Laminate	Trade Secret	61.36		0.1588	
	Solder Mask	Trade Secret	17.47		0.0452	
	Copper	7440-50-8	16.11	Metal Layer	0.0417	
	Nickel	7440-02-0	4.29	Metal Layer	0.0111	
	Gold	7440-57-5	0.77	Metal Layer	0.0020	
Bond Wire					0.0104	0.83%
	Gold	7440-57-5	99.00		0.010287129	
	Silver	7440-22-4	0.0025		0.000000260	
	Copper	7440-50-8	0.0005		0.000000052	
	Iron	7439-89-6	0.0005		0.000000052	
	Calcium	7440-70-2	0.0020		0.000000208	
	Palladium	7440-05-3	0.9900		0.000102871	
	Magnesium	7439-95-4	0.0005		0.000000052	
Solder Balls					0.3386	27.03%
	Tin	7440-31-5	95.50		0.3234	
	Silver	7440-22-4	4.00		0.0135	
	Copper	7440-50-8	0.50		0.0017	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
5/12/06	1.1	100% Material Declaration.
9/27/06	1.2	Updated component descriptions.